

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-25 (canceled)

Claim 26 (Currently amended): ~~A contact structure~~ A test apparatus for testing an electronic device, said apparatus comprising:

a substrate; and

a plurality of probes, each said probe comprising palladium and further comprising:

a contact tip disposed to make a temporary, pressure based connection with a terminal of said electronic device during testing of said electronic device;

a base secured to [[a]] said substrate; and

a body disposed at least in part away from said substrate, wherein said body is attached to said base and ~~comprises palladium~~ said tip is attached to said body.

Claim 27 (Currently amended): The ~~contact structure~~ test apparatus of claim 26, wherein said ~~body probe~~ probe comprises a palladium cobalt alloy.

Claim 28 (Currently amended): The ~~contact structure~~ test apparatus of claim 26, wherein said ~~body probe~~ probe comprises a palladium rhodium alloy.

Claim 29 (Currently amended): The ~~contact structure~~ test apparatus of claim 26, wherein said ~~body probe~~ probe comprises a palladium tungsten alloy.

Claim 30 (Canceled)

Claim 31 (Currently amended): The ~~contact structure~~ test apparatus of ~~claim 30~~ claim 26, wherein said tip comprises palladium.

Claim 32 (Currently amended): The ~~contact structure~~ test apparatus of ~~claim 30~~ claim 26, wherein said tip comprises a palladium cobalt alloy.

Claim 33 (Currently amended): The ~~contact structure~~ test apparatus of ~~claim 30~~ claim 26, wherein said tip is integrally formed with said body.

Claim 34 (Currently amended): The ~~contact structure~~ test apparatus of claim 26, wherein a majority of said body comprises palladium.

Claim 35 (Withdrawn): The ~~contact structure~~ test apparatus of claim 26, wherein said base and said body are integrally formed.

Claim 36 (Currently amended): The ~~contact structure~~ test apparatus of claim 26, wherein said body comprises a beam that is structurally distinct from said base.

Claim 37 (Currently amended): The ~~contact structure~~ test apparatus of claim 26, wherein said contact structure is resilient.

Claim 38 (Currently amended): The ~~contact structure~~ test apparatus of claim 26, wherein said ~~beam~~ probe comprises a plurality of layers of material, wherein at least one of said layers comprises palladium.

Claims 39 and 40 (Canceled)

Claim 41 (Currently amended): The ~~contact structure~~ test apparatus of claim 26, wherein said ~~base is attached to~~ test apparatus is a probe card assembly.

Claim 42 (Currently amended): ~~A contact structure~~ A test apparatus for testing an electronic device, said test apparatus comprising:

a substrate; and

a plurality of probes attached to said substrate and comprising contact tips disposed to make temporary, pressure based connections with terminals of said electronic device to be tested, wherein each said probe comprises ~~a substrate; and probing means for an electronic device, said probing means secured to said substrate and comprising palladium.~~

Claim 43 (Currently amended): The ~~contact structure~~ test apparatus of claim 42, wherein ~~said probing means~~ each said probe comprises a palladium cobalt alloy.

Claims 44-47 (Canceled)

Claim 48 (Currently amended): The ~~contact structure~~ test apparatus of claim 42, wherein ~~said substrate composes~~ test apparatus is a probe card assembly.

Claims 49-53 (Canceled)

Claim 54 (Currently amended): The ~~interconnect structure~~ electronic component of ~~claim 53~~ claim 66, wherein said tip comprises a palladium cobalt alloy.

Claims 55 and 56 (Canceled)

Claim 57 (Currently amended) The ~~interconnect structure~~ electronic component of ~~claim 56~~ claim 66, wherein said ~~first portion~~ base comprises a post and said ~~second portion comprises a tip, said interconnect structure further comprising~~ body comprises a beam to which said post and said tip are attached.

Claim 58 (Currently amended): The ~~interconnect structure~~ electronic component of claim 57, wherein said beam is cantilevered.

Claim 59 (Currently amended): The ~~interconnect structure~~ electronic component of ~~claim 49~~ claim 66, wherein said interconnect structure is resilient.

Claim 60 (Currently amended): The ~~interconnect structure~~ electronic component of ~~claim 49~~ claim 66, wherein said interconnect structure comprises a plurality of layers of material, ~~wherein at least one of said layers comprises palladium.~~

Claims 61-65 (Canceled)

Claim 66 (New): An electronic component comprising a plurality of interconnect structures, each said interconnect structure comprising:

- a base attach to a terminal of said electronic component;
 - a tip configured to contact a terminal of an electronic device and thereby establish a connection between said electronic component and said electronic device; and
 - a body connecting said base with said tip,
- wherein said interconnect structure comprises a palladium cobalt alloy.

Claim 67 (New): The electronic component of claim 66, wherein said body and said tip are distinct structures attached one to another.

Claim 68 (New): The electronic component of claim 66, wherein said body and said base are distinct structures attached one to another.

Claim 69 (New): The electronic component of claim 66, wherein said base and said body are distinct structures attached one to another, and said body and said tip are distinct structures attached one to another.

Claim 70 (New): The electronic component of claim 69, wherein each interconnection structure is configured to contact one of said terminals of said electronic device such that no two interconnection structures contact a same terminal of said electronic device.

Claim 71 (New): The electronic component of claim 70, wherein base is attached to said body at a first end of said body and said tip is attached to said body at a second end of said body, and said second end of said body is moveable such that said second end of said body deflects upon contact with a terminal of said electronic device.

Claim 72 (New): The electronic component of claim 66, wherein said palladium cobalt alloy is electroplated.

Claim 73 (New): The test apparatus of claim 26, wherein said body and said base are distinct structures.

Claim 74 (New): The test apparatus of claim 26, wherein said body and said tip are distinct structures.

Claim 75 (New): The test apparatus of claim 74, wherein said body and said base are distinct structures.

Claim 76 (New): The test apparatus of claim 26, wherein each probe is configured to contact one of said terminals of said electronic device such that no two probes contact a same terminal of said electronic device.

Claim 77 (New): The test apparatus of claim 76, wherein said base is attached to said body at a first end of said body and said tip is attached to said body at a second end of said body, and said second end of said body is moveable such that said second end of said body deflects upon contact with a terminal of said electronic device.

Claim 78 (New): The test apparatus of claim 26, wherein said palladium is electroplated.

Claim 79 (New): The test apparatus of claim 42, wherein each said probe further comprises a post attached to a terminal on said substrate and a body, said body connecting said post and said tip.

Claim 80 (New): The test apparatus of claim 79, wherein said post and said body are distinct structures attached one to another.

Claim 81 (New): The test apparatus of claim 80, wherein said tip and said body are distinct structures attached to one another.

Claim 82 (New): The test apparatus of claim 79, wherein said tip and said body are distinct structures attached to one another.

Claim 83 (New): The test apparatus of claim 79, wherein each probe is configured to contact one of said terminals of said electronic device such that no two probes contact a same terminal of said electronic device.

Claim 84 (New): The test apparatus of claim 79, wherein said post is attached to said body at a first end of said body and said tip is attached to said body at a second end of said body, and said second end of said body is moveable such that said second end of said body deflects upon contact with a terminal of said electronic device.

Claim 85 (New): The test apparatus of claim 42, wherein said palladium is electroplated.